

08/984615

Sub all

ABSTRACT

5 Semiconductor chip assemblies incorporating
flexible, sheet-like elements having terminals thereon
overlying the front or rear face of the chip to provide
a compact unit. The terminals on the sheet-like element
are movable with respect to the chip, so as to
compensate for thermal expansion. A resilient element
such as a compliant layer interposed between the chip
and terminals permits independent movement of the
10 individual terminals toward the chip driving engagement
with a test probe assembly so as to permit reliable
engagement despite tolerances.

08984615 120397